



**ULTRA FAST CURE HIGH TEMPERATURE EPOXY ADHESIVE E-109**

E-109 is a high performance silica filled single component adhesive which cure in 5 minutes or less with excellent shear strength in combination with use temperature of 200°C. Has very low outgassing during cure making it especially suitable for use in switches, sensors and other electronic applications. Rapid cure speed make it an excellent choice for automatic assembly using IR. induction, or hot air cure. Suitable for use with automatic dispensing equipment.

**PROPERTIES**

appearance.....	tan non sag paste
specific gravity.....	1.3
viscosity.....	thixotropic
lap shear aluminum to aluminum, cured 5 minutes at 150°C, tested at RT.....	3,100 psi
tested at 125°C.....	2,280 psi
tested at 160°C.....	560 psi
tested at 200°C.....	320 psi
maximum continuous use temperature.....	210°C

**CURE CONDITIONS**

- Cure according to one of the following cure schedules:
- 5 minutes 150°C
- 10 minutes 140°C
- 20 minutes 130°C

All times are for time at the specified temperature as measured at the bondline. Time must be allowed for the bondline to reach temperature. This can be minimized by using high speed curing methods such as infrared, induction, hot air tunnel etc. Shorter times can be realized if reduced properties are acceptable or if higher cure temperatures can be used. Do not exceed 210°C.

**STORAGE**

Refrigerated storage is desirable. Shelf life is at least 12 months at 0°C, 4 months at room temperature (18°C)

**HANDLING**

All contact with skin or ingestion should be avoided in accordance with normal handling procedures with epoxy resins. No warranty or guarantee is made regarding this material. The user should determine suitability for a given application. For more information see MSDS.

**PRICING**

2 oz. \$40.00 ea., 1 lb. \$100 ea.

1441 Dorcey Road • Winchester, OH 45697 • mail@koford.com